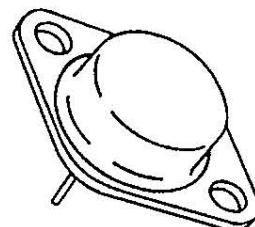


Description

These devices are n-channel, enhancement mode, power MOSFETs designed especially for high speed applications, such as switching power supplies, converters, AC and DC motor controls, relay and solenoid drivers and other pulse circuits.

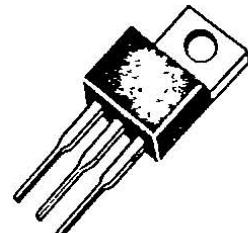
- Low $R_{DS(on)}$
- V_{GS} Rated at $\pm 20V$
- Silicon Gate for Fast Switching Speeds
- $I_{DSS}, V_{DS(on)}$, Specified at Elevated Temperature
- Rugged
- Low Drive Requirements
- Ease of Paralleling

TO-204AA



IS0002CF

TO-220AB



IS0001AF

IRF420

IRF421

IRF422

IRF423

IRF820

IRF821

IRF822

IRF823

MTP2N45

MTP2N50

Product Summary

Part Number	V_{DSS}	$R_{DS(on)}$	I_D at $T_c=25$	I_D at $T_c=100$	Case Style
IRF420	500V	3.0 Ω	2.5A	1.5A	TO-204AA
IRF421	450V	3.0 Ω	2.5A	1.5A	
IRF422	500V	4.0 Ω	2.0A	1.0A	
IRF423	450V	4.0 Ω	2.0A	1.0A	
IRF820	500V	3.0 Ω	2.5A	1.5A	TO-220AB
IRF821	450V	3.0 Ω	2.5A	1.5A	
IRF822	500V	4.0 Ω	2.0A	1.0A	
IRF823	450V	4.0 Ω	2.0A	1.0A	
MTP2N45	450V	4.0 Ω	3.0A	2.0A	
MTP2N50	500V	4.0 Ω	3.0A	2.0A	

Notes

For information concerning connection diagram and package outline, refer to Section 7.



**IRF420-423/IRF820-823
MTP2N45/2N50
N-Channel Power MOSFETs
3.0A, 450V/500V**

Maximum Ratings

Symbol	Characteristic	Rating IRF420/422 IRF820/822 MTP2N50	Rating IRF421/423 IRF821/823 MTP2N45	Unit
V _{DSS}	Drain to Source Voltage 1	500	450	V
V _{DGR}	Drain to Gate Voltage 1 $R_{GS}=20\text{k}\Omega$	500	450	V
V _{GS}	Gate to Source Voltage	± 20	± 20	V
T _J , T _{stg}	Operating Junction and Storage Temperatures	-55 to +150	-55 to +150	
T _L	Maximum Lead Temperature for Soldering Purposes, 1/8" From Case for 5s	275	275	

Maximum Thermal Characteristics

		IRF420-423/ IRF820-823	MTP2N45/2N50	
R _{θJC}	Thermal Resistance, Junction to Case	3.12	1.67	/W
R _{θJA}	Thermal Resistance, Junction to Ambient	30/80	80	/W
P _D	Total Power Dissipation at T _c =25	40	75	W
I _{DM}	Pulsed Drain Current ²	10	10	A

Electrical Characteristics (T_c=25 unless otherwise noted)

Symbol	Characteristic	Min	Max	Unit	Test Conditions
Off Characteristics					
V _{(BR)DSS}	Drain Source Breakdown Voltage ¹ IRF420/422/820/822 MTP2N50 IRF421/423/821/823/ MTP2N45			V	V _{GS} =0V, I _D =250μA
		500			
		450			
I _{DSS}	Zero Gate Voltage Drain Current		250	μA	V _{DS} =Rated V _{DSS} , V _{GS} =0V
			1000	μA	V _{DS} =0.8 x Rated V _{DSS} , V _{GS} =0V, T _c =125
I _{GSS}	Gate-Body Leakage Current IRF420-423 IRF820-823/MTP2N45/50			nA	V _{GS} =±20V, V _{DS} =0V
			±100		
			±500		

Electrical Characteristics (Cont.) ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Characteristic	Min	Max	Unit	Test Conditions
On characteristics					
$V_{GS(th)}$	Gate Threshold Voltage	2.0	4.0	V	$I_D=250\mu A, V_{DS}=V_{GS}$ $I_D=1.0mA, V_{DS}=V_{GS}$
	IRF420-423/IRF820-823 MTP2N45/MTP2N50	2.0	4.5		
$R_{DS(on)}$	Static Drain-Source On-Resistance 2 IRF420/421/820/821 IRF422/423/822/823 MTP2N45/50			Ω	$V_{GS}=10V, I_D=1.0A$
			3.0		
			4.0		
			4.0		
$V_{DS(on)}$	Drain-Source On-Voltage2 MTP2N45/50			V	$V_{GS}=10V; I_D=2.0A$ $V_{GS}=10V; I_D=1.0A$ $T_c=100^\circ C$
			10		
			8		
g_{fs}	Forward Transconductance	1.0		S(Ü)	$V_{DS}=10V, I_D=1.0A$

Dynamic Characteristics

Ciss	Input Capacitance		400	pF	$V_{DS}=25V, V_{GS}=0V$ $f=1.0MHz$
Coss	Output Capacitance		100	pF	
Crss	Reverse Transfer Capacitance		40	pF	

Switching Characteristics ($T_c=25^\circ C$, Figure 1.2)³

td(on)	Turn-On Delay Time		40	ns	$V_{DD}=250V, I_D=1.0A$ $V_{GS}=10V, R_{GEN}=50 \Omega$ $R_{GS}=50 \Omega$
tr	Rise Time		50	ns	
td(off)	Turn-Off Delay Time		60	ns	
tf	Fall Time		60	ns	
Qg	Total Gate Charge		15	nC	$V_{GS}=10V, I_D=3.0A$ $V_{DD}=200V$

Symbol	Characteristic	Typ	Max	Unit	Test Conditions
Source-Drain Diode Characteristics					
V_{SD}	Diode Forward Voltage		1.4	V	$I_S=2.5A; V_{GS}=0V$
			1.3	V	$I_S=2.0A; V_{GS}=0V$
trr	Reverse Recovery Time	600		ns	$I_S=2.5A; dI_S/dt=100A/\mu s$

Notes

1. $T_J=+25^\circ C$ to $+150^\circ C$
2. Pulse width limited by T_J
3. Switching time measurements performed on LEM TR-58 test equipment.

Typical Electrical Characteristics

Figure 1 Switching Test Circuit

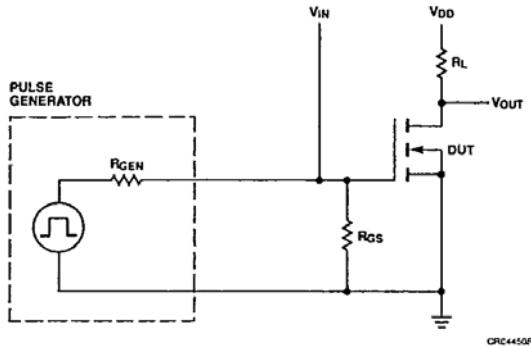
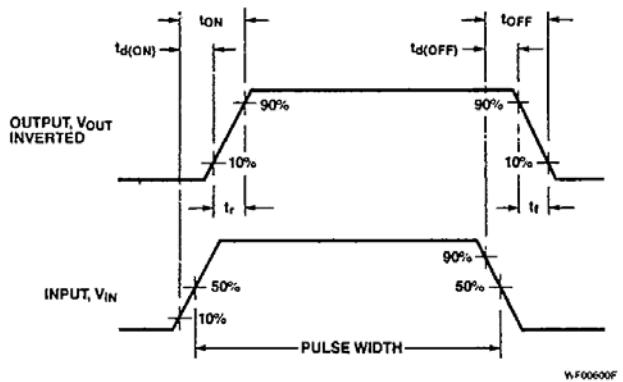


Figure 2 Switching Waveforms



Typical Performance Curves

Figure 3 Output Characteristics

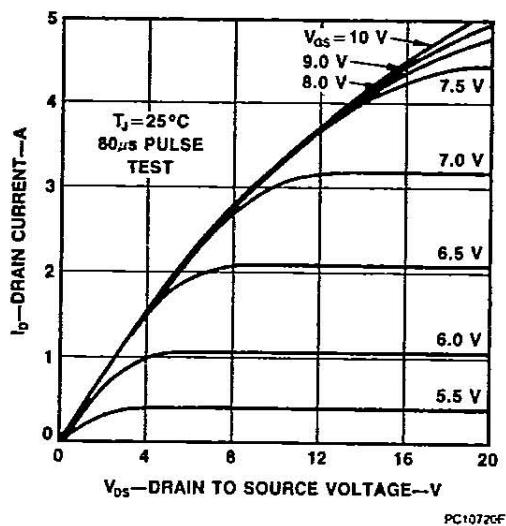


Figure 4 Static Drain to Source Resistance

Vs Drain Current

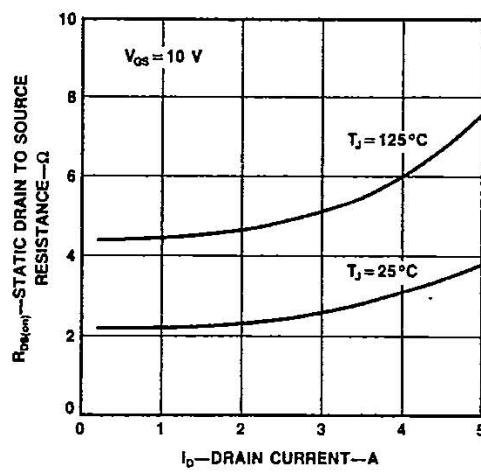


Figure 5 Transfer Characteristics

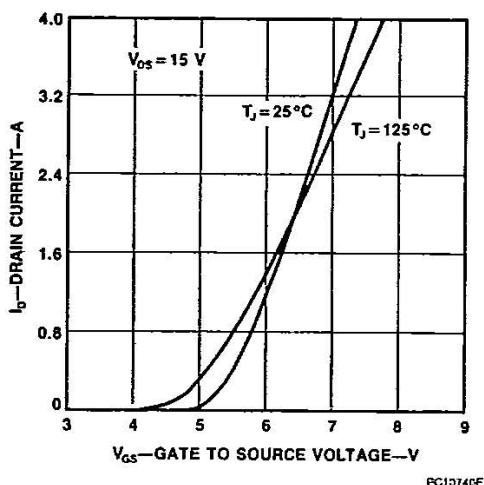
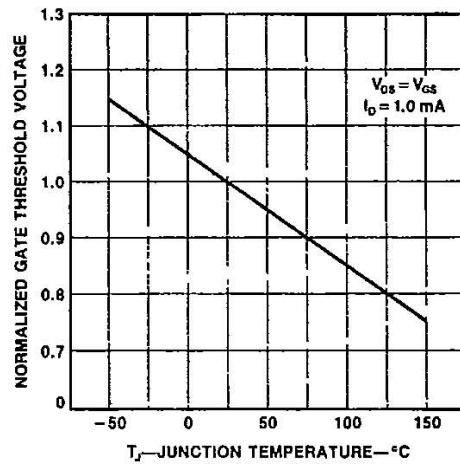


Figure 6 Temperature Variation of Gate to Source Threshold Voltage



Typical Performance Curves (Cont.)

Figure 7 Capacitance vs Drain to Source Voltage

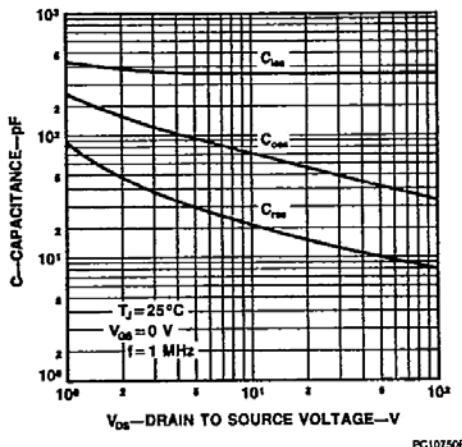


Figure 9 Forward Biased Safe Operating Area for IRF420-423 and IRF820-823

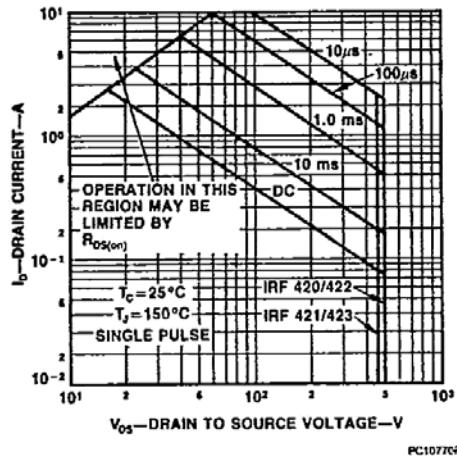


Figure 11 Forward Biased Safe Operating Area for MTP2N45/2N50

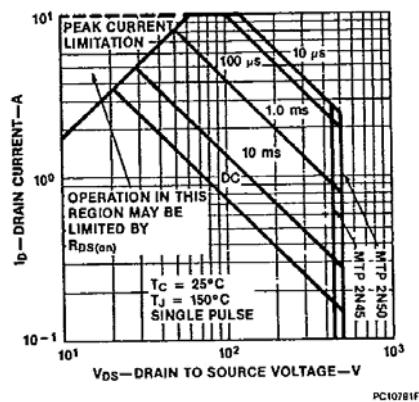


Figure 8 Gate to Source Voltage VS Total Gate Charge

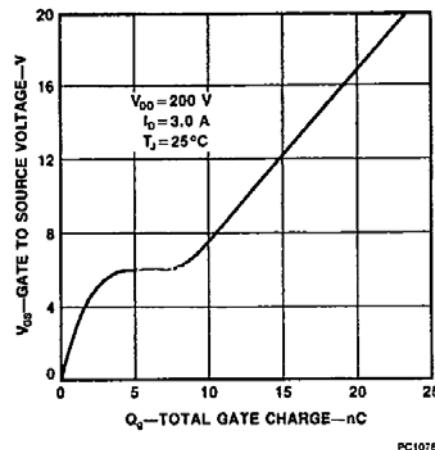


Figure 10 Transient Thermal Resistance vs Time for IRF420-423 and IRF820-823

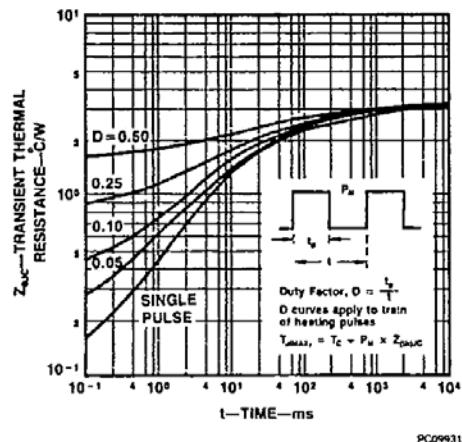


Figure 12 Transient Thermal Resistance vs time for MTP2N45/2N50

